

A

B

C

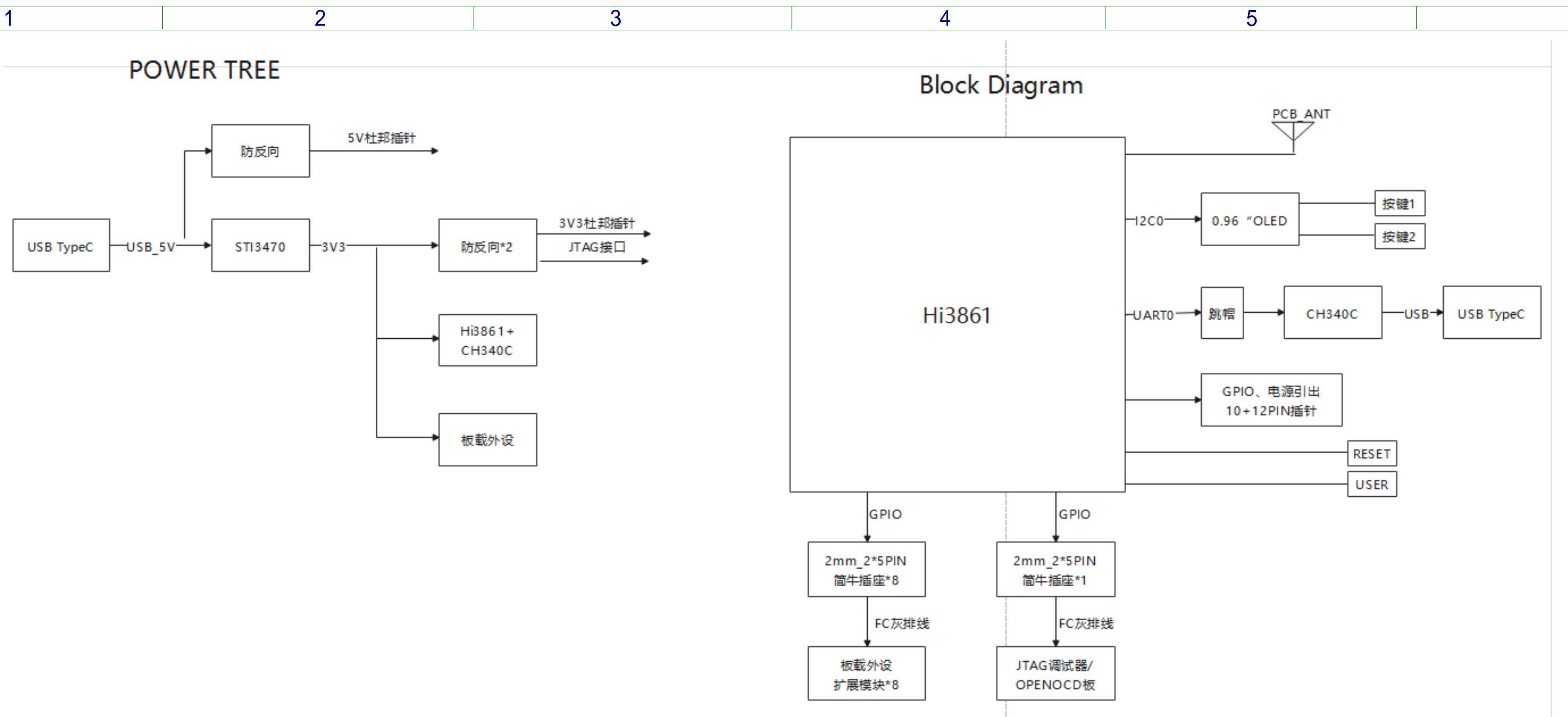
D

A

B

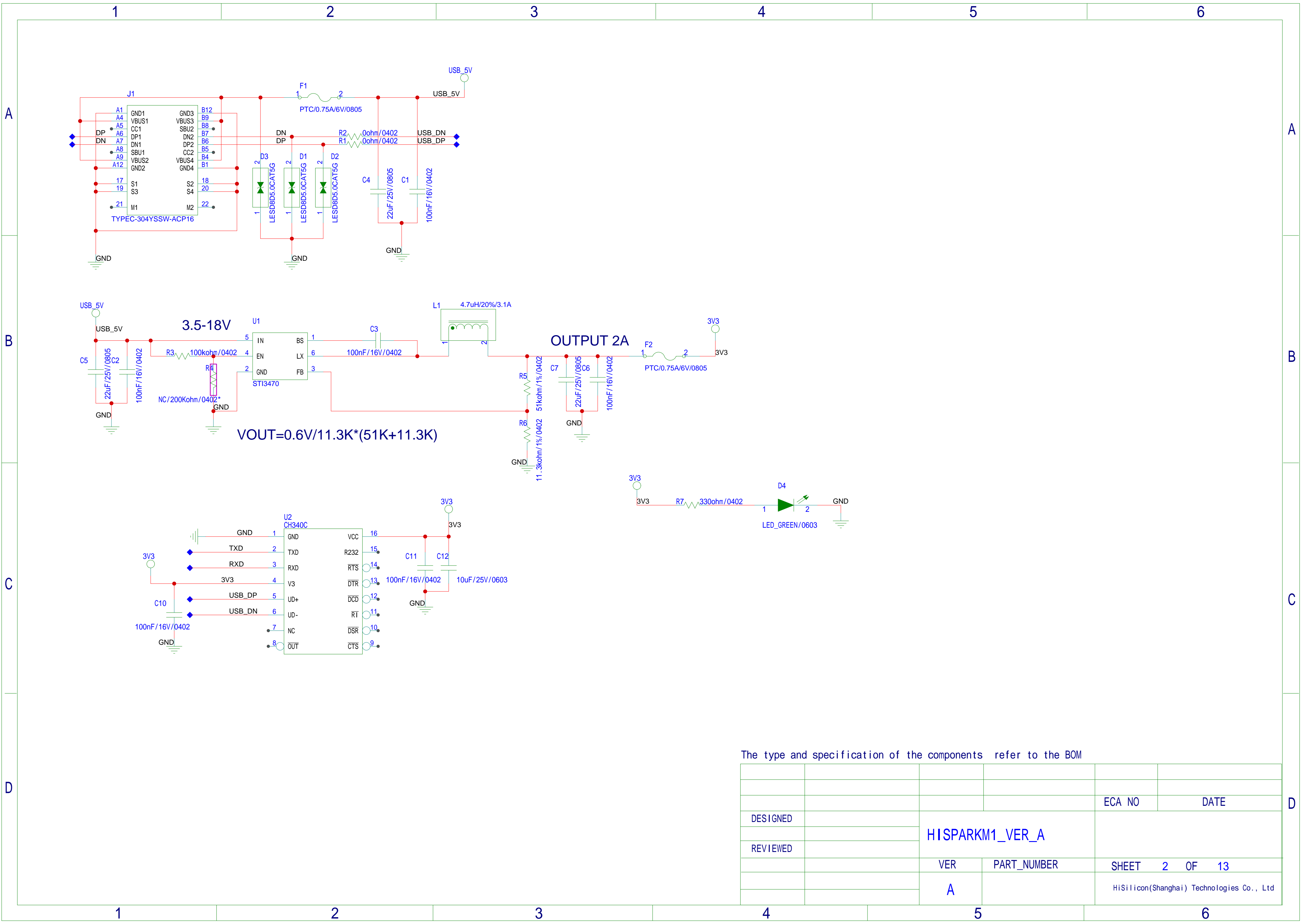
C

D



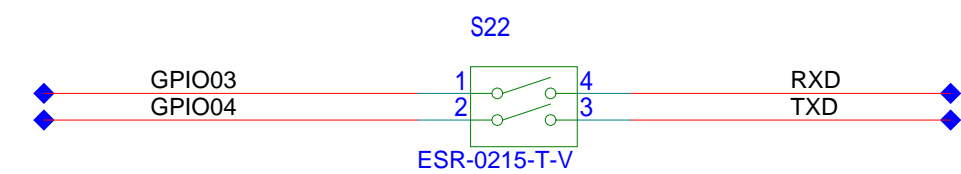
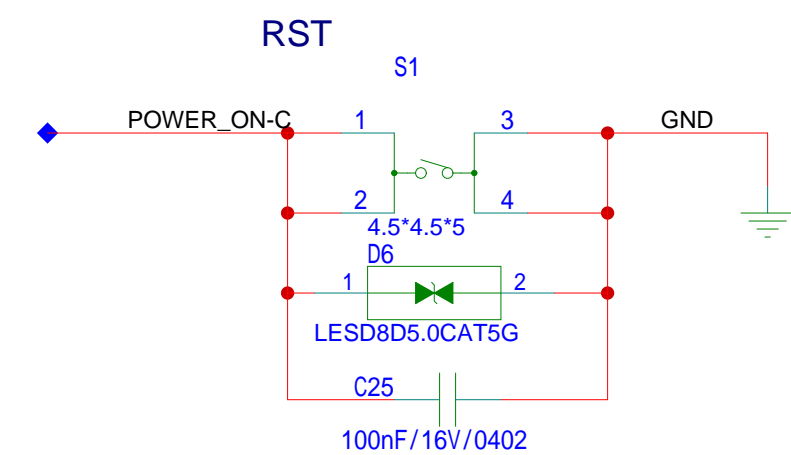
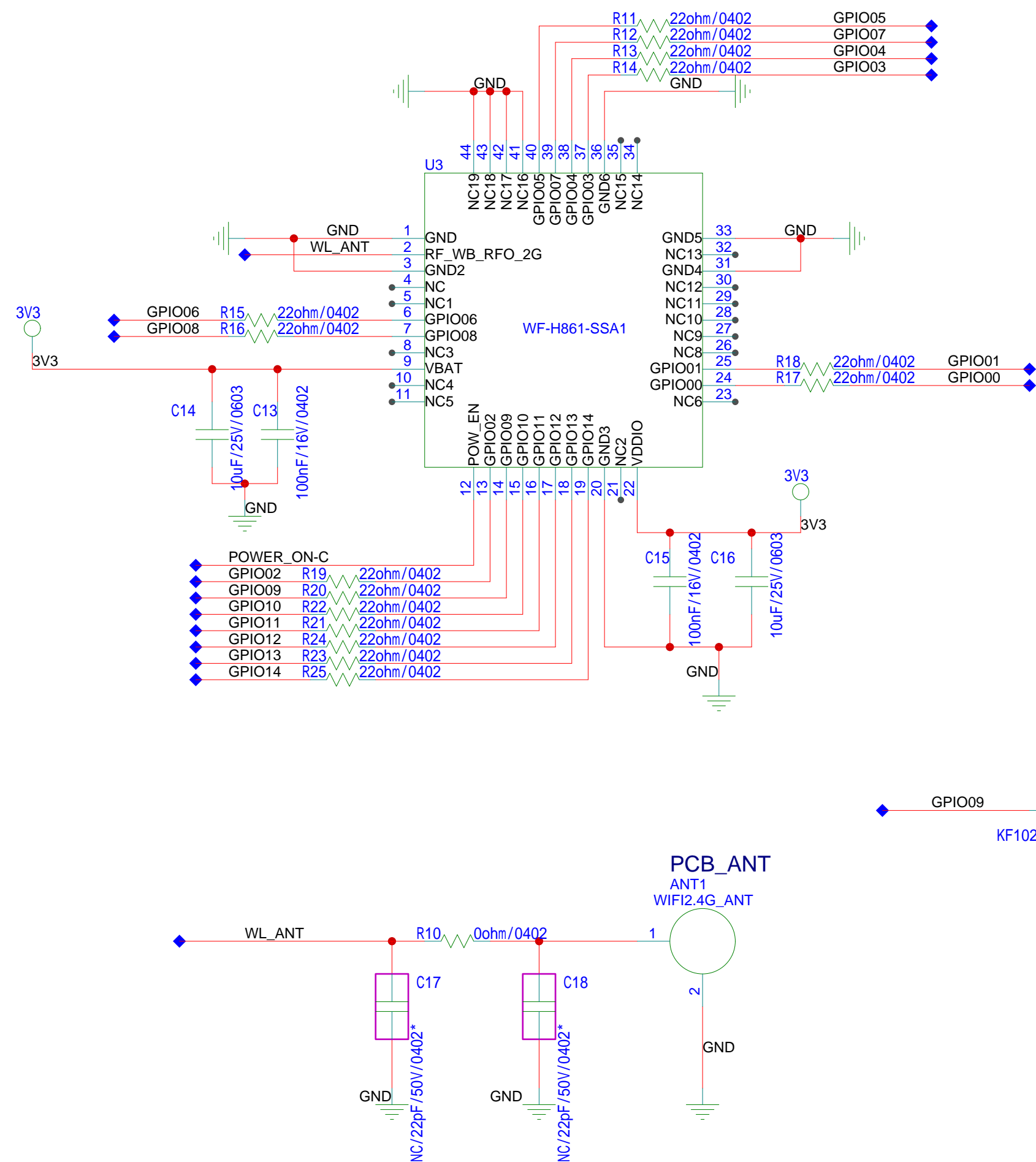
The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKM1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET	1 OF 13
		A		HiSilicon(Shanghai) Technologies Co., Ltd	



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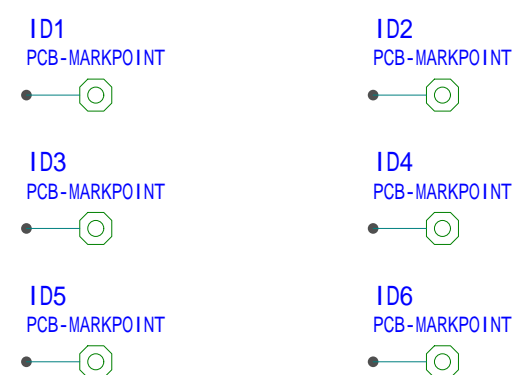
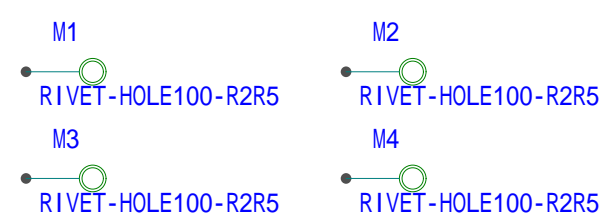
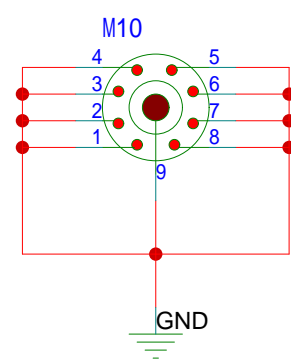
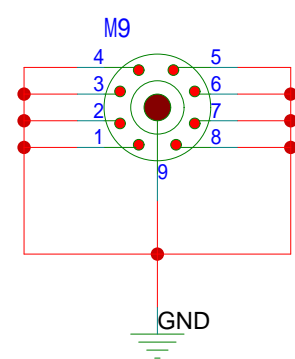
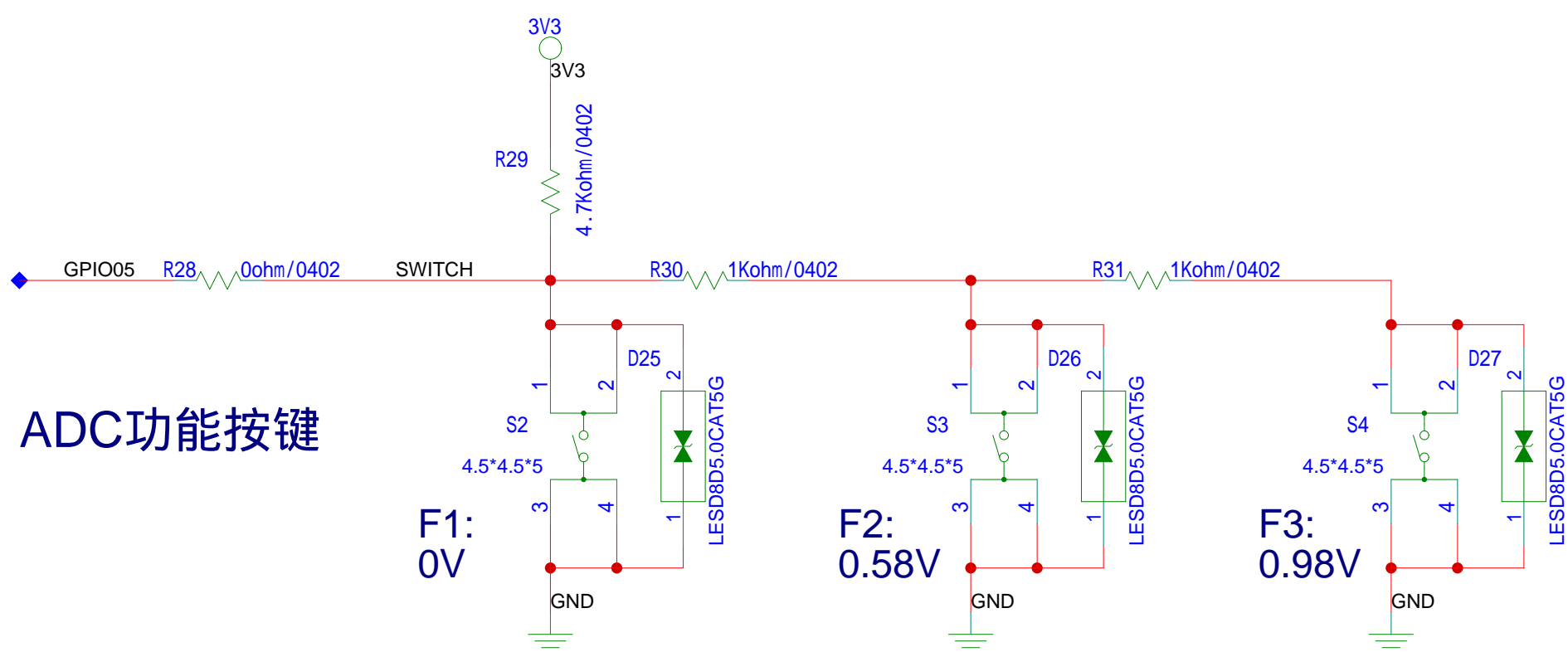
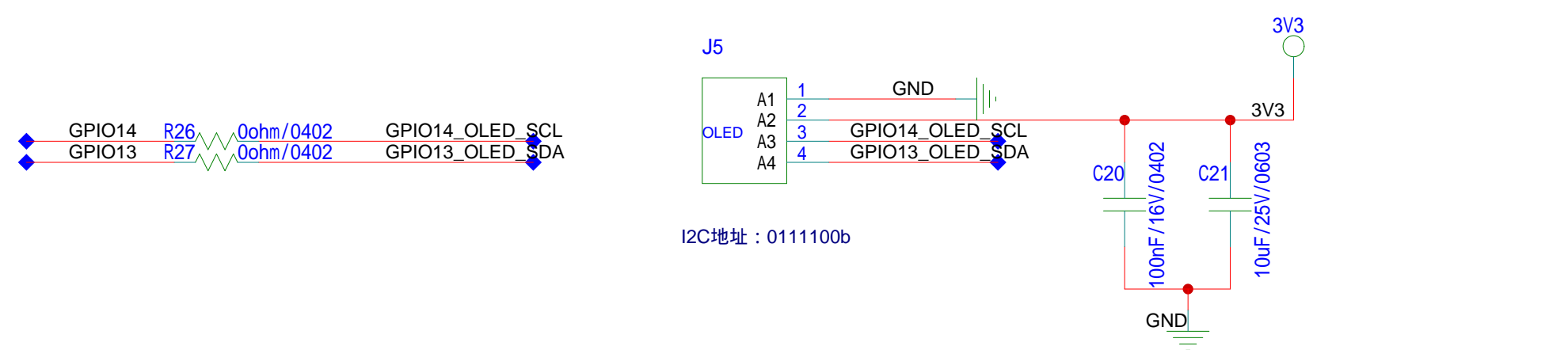
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		VER	PART_NUMBER	SHEET	2 OF 13
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- 1.使用USB口调试时，需拨通开关；
- 2.使用UART跳杜邦线直连调试时，需断开开关；
- 3.连接OPENOCD板在SWD工作模式时必须断开开关；USB烧录和通信时必须拨通开关。

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拼板孔

光学定位

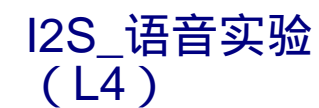
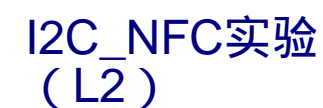
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REVIEWED					
		VER	PART_NUMBER	SHEET	4 OF 13
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外设供电

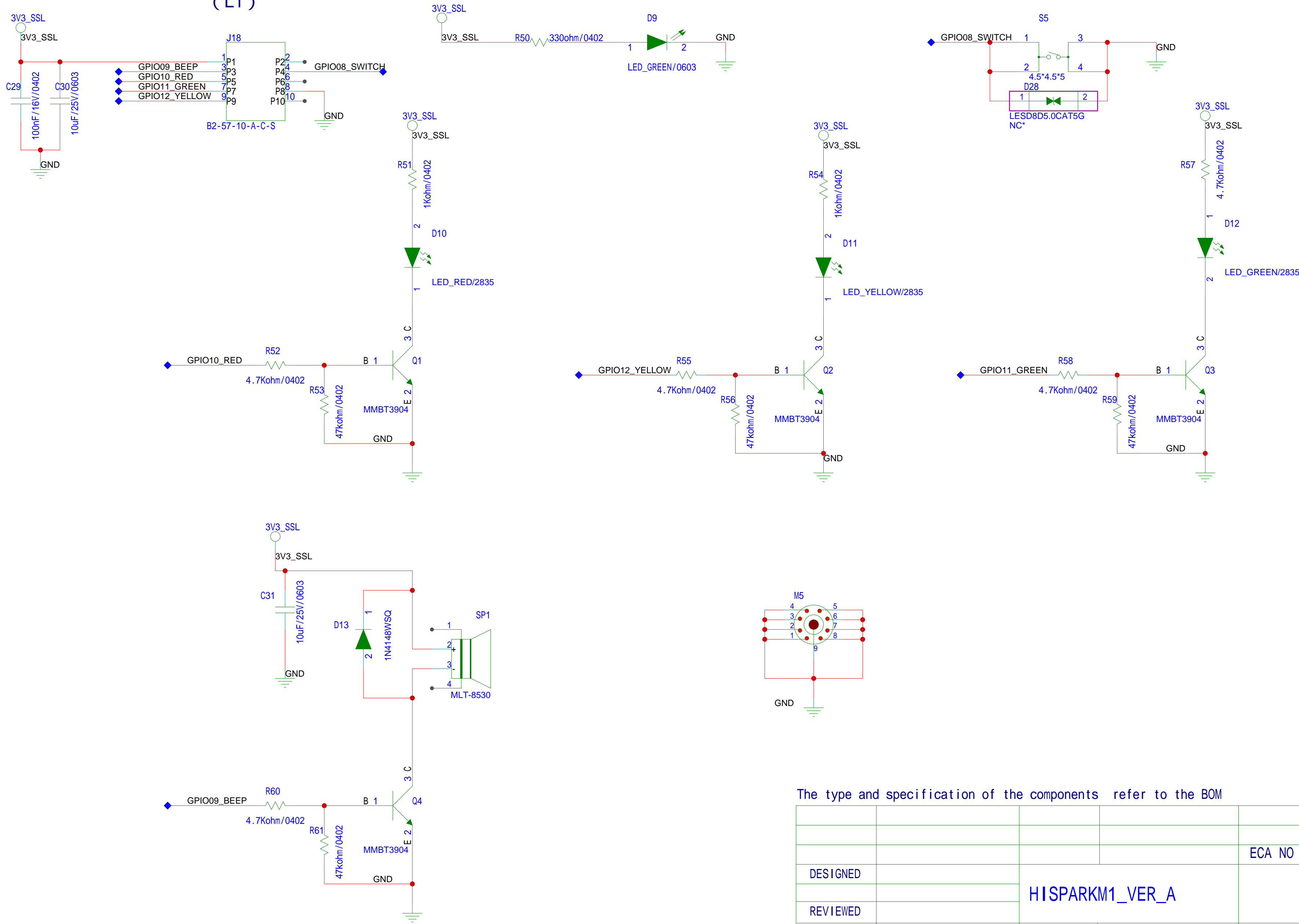
防止使用者接可单独供电的外设时，外设反供电给MCU



JTAG连接器

1

PWM_交通灯实验
(L1)



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A



C

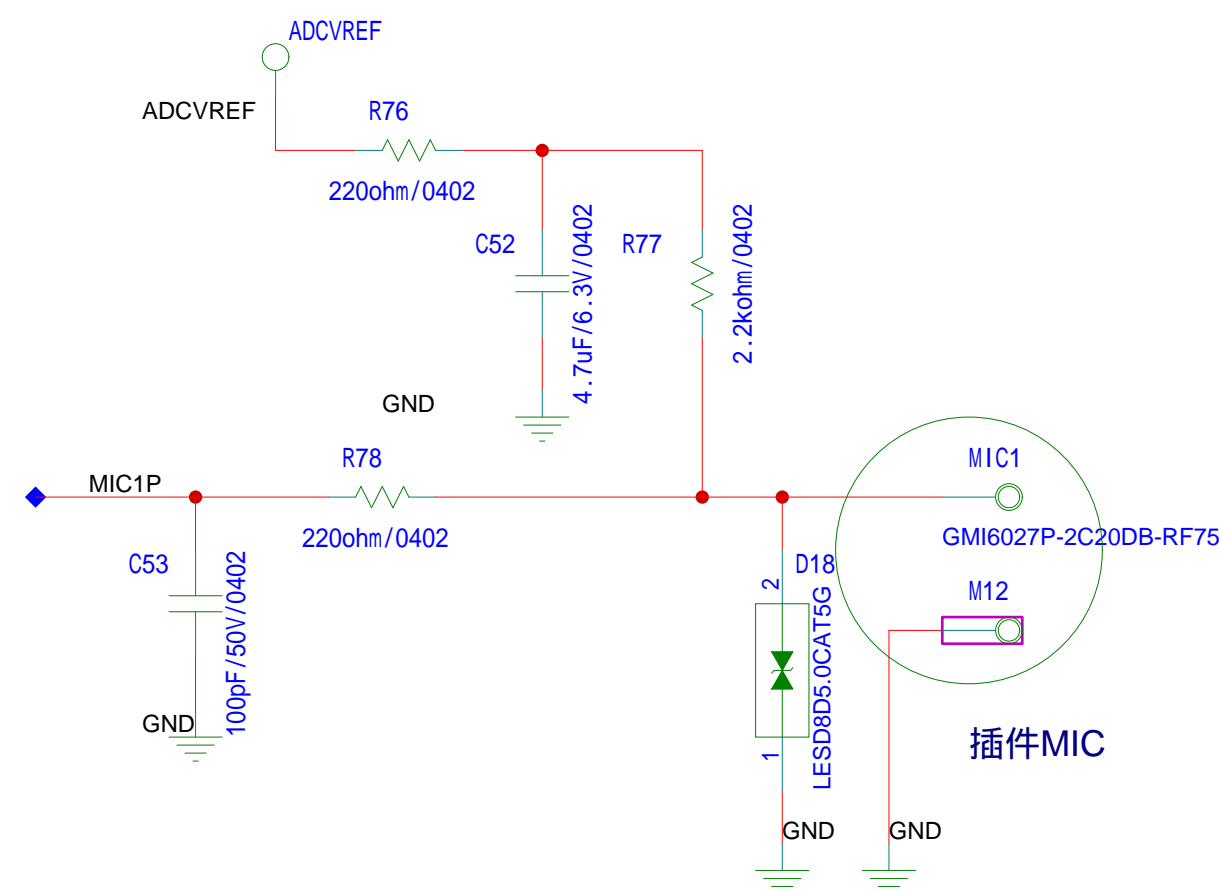
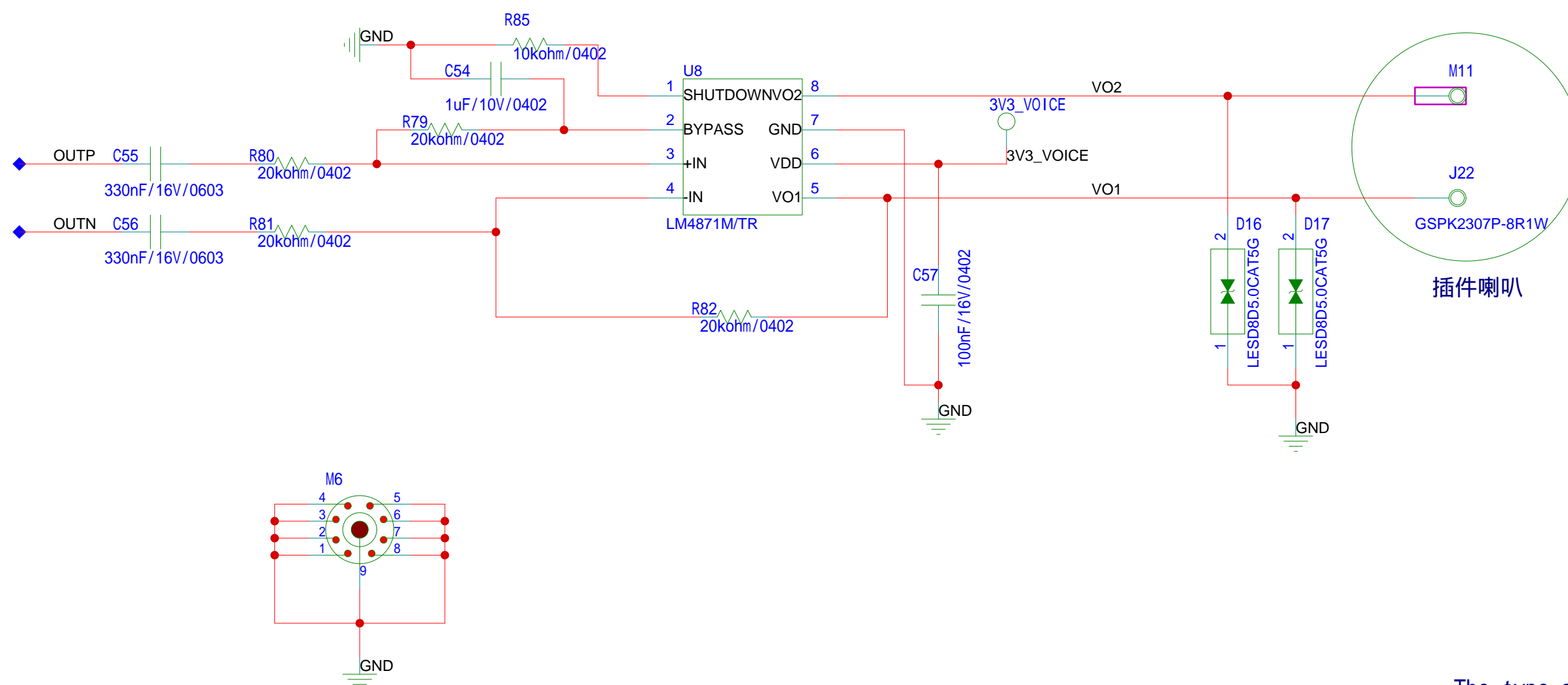
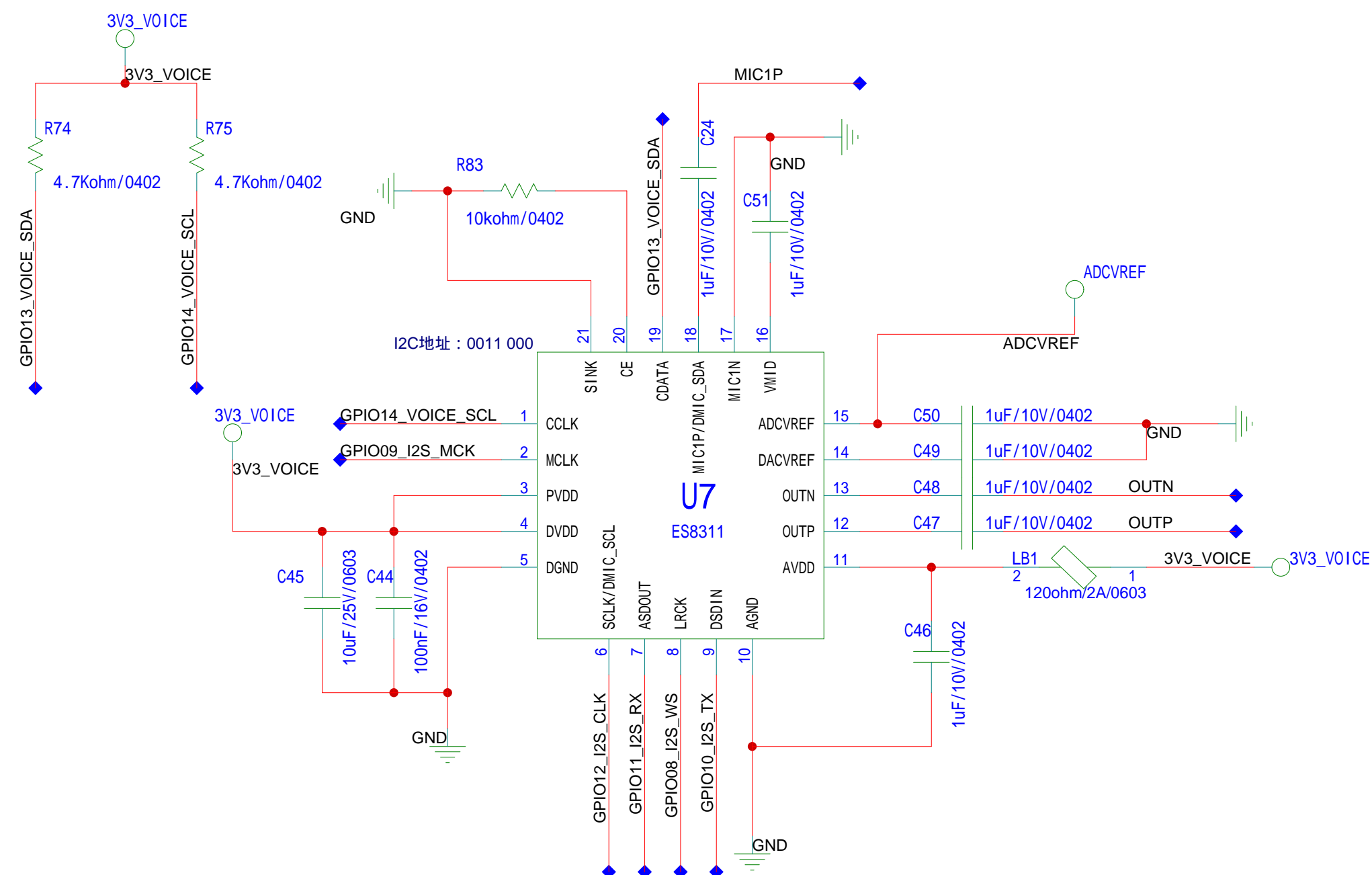
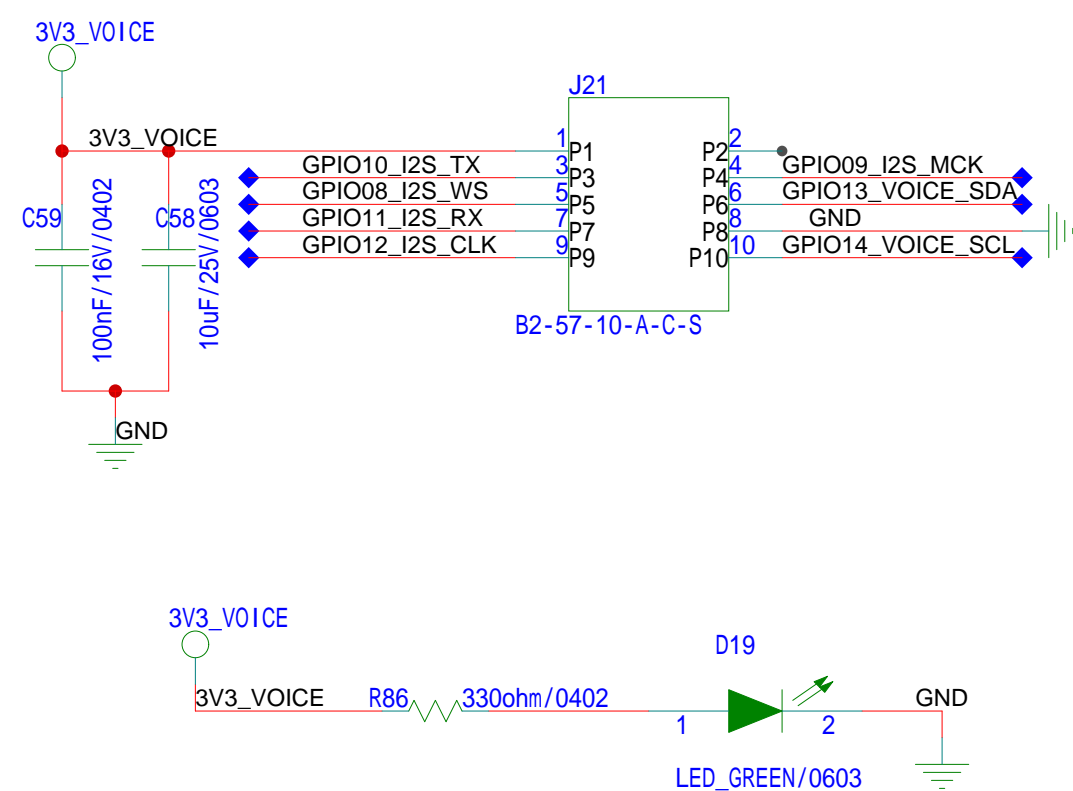
D

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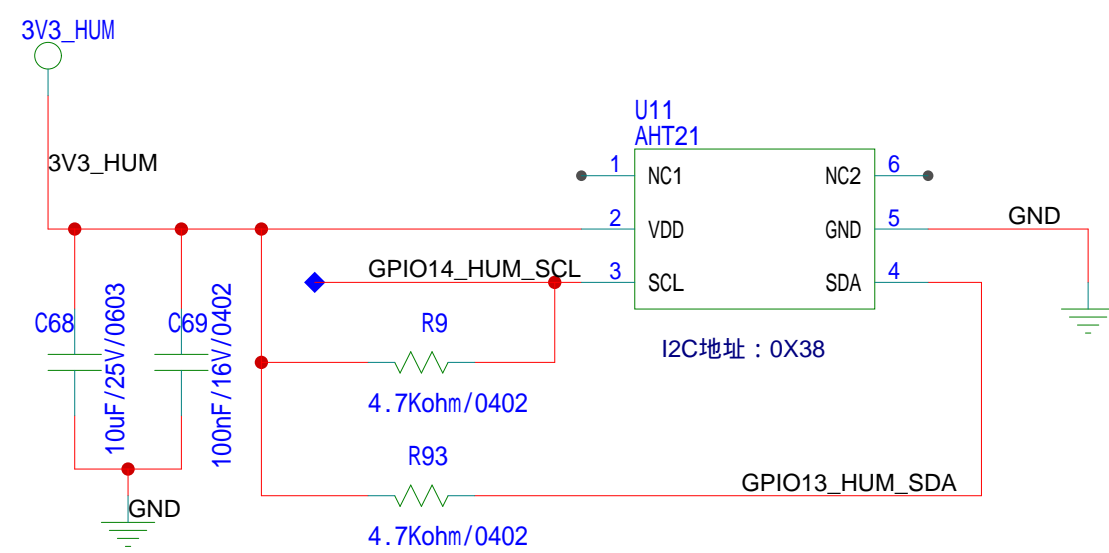
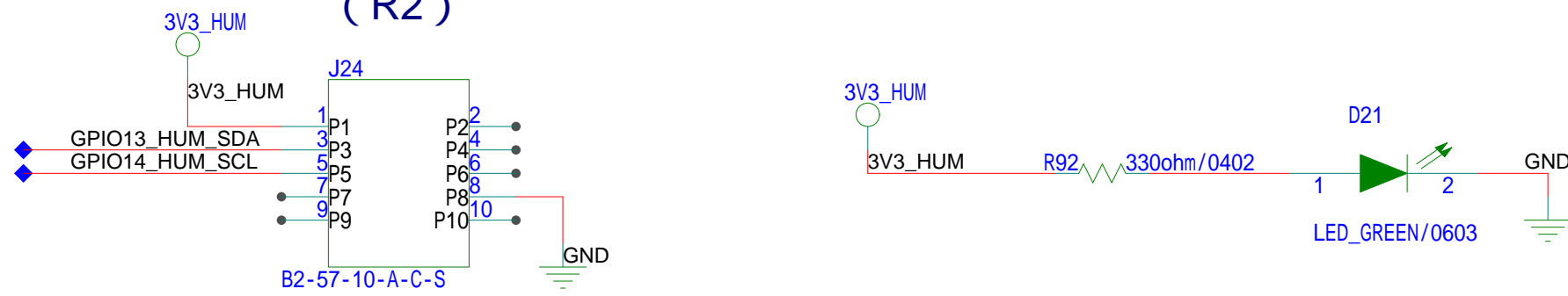
A



D

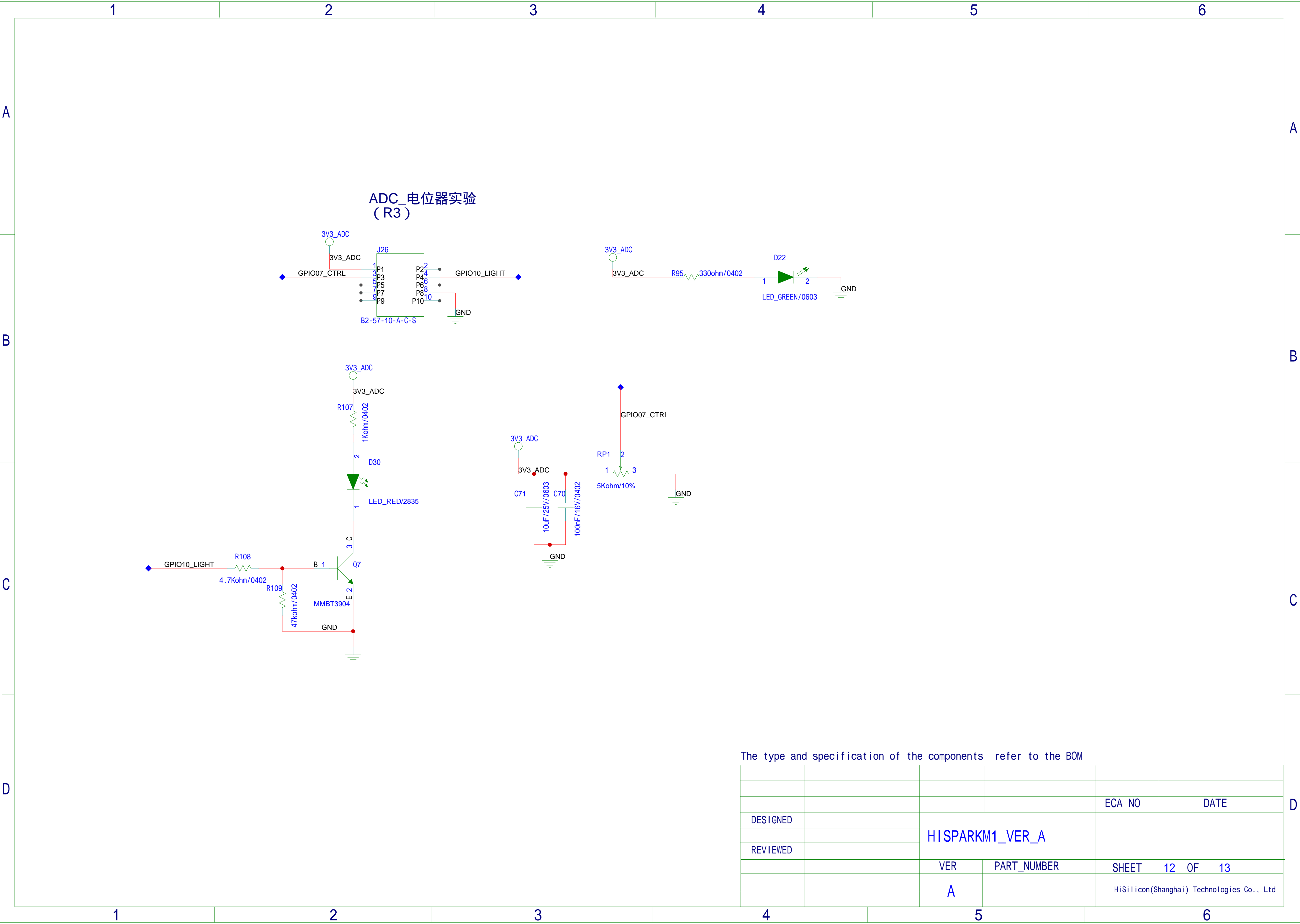
D

I2C_温湿度实验 (R2)

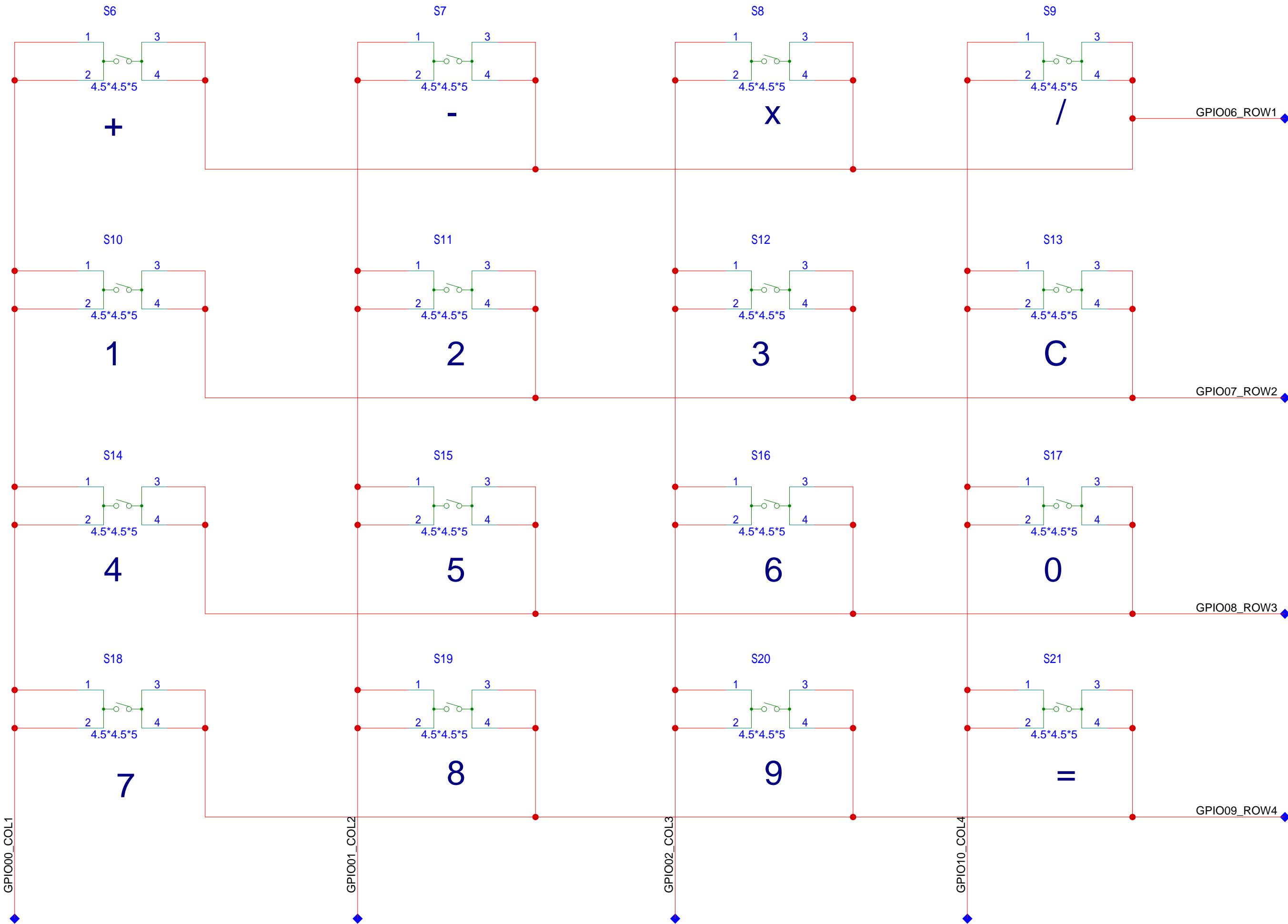
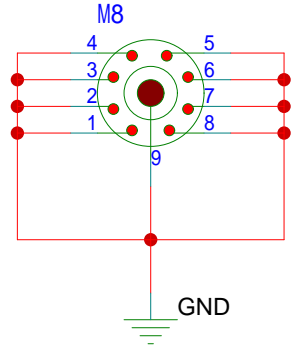
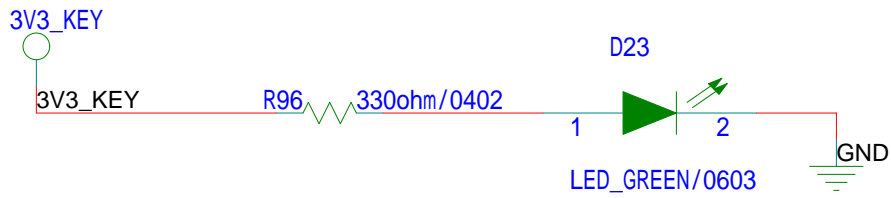
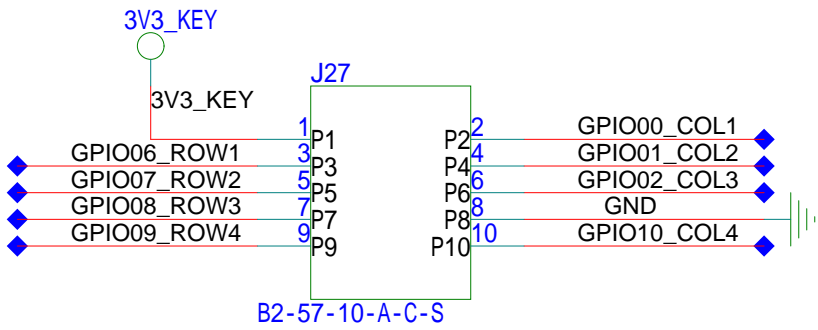


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IO 键盘矩阵实验 (R4)



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